

ENRZ Advanced Modulation for Low Latency Applications

OIF CEI-56G – Signal Integrity to the Forefront

David R Stauffer

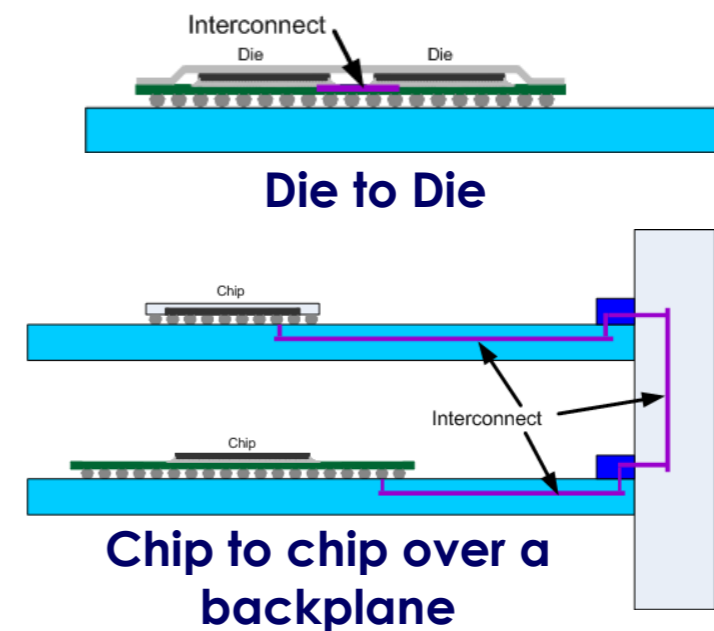
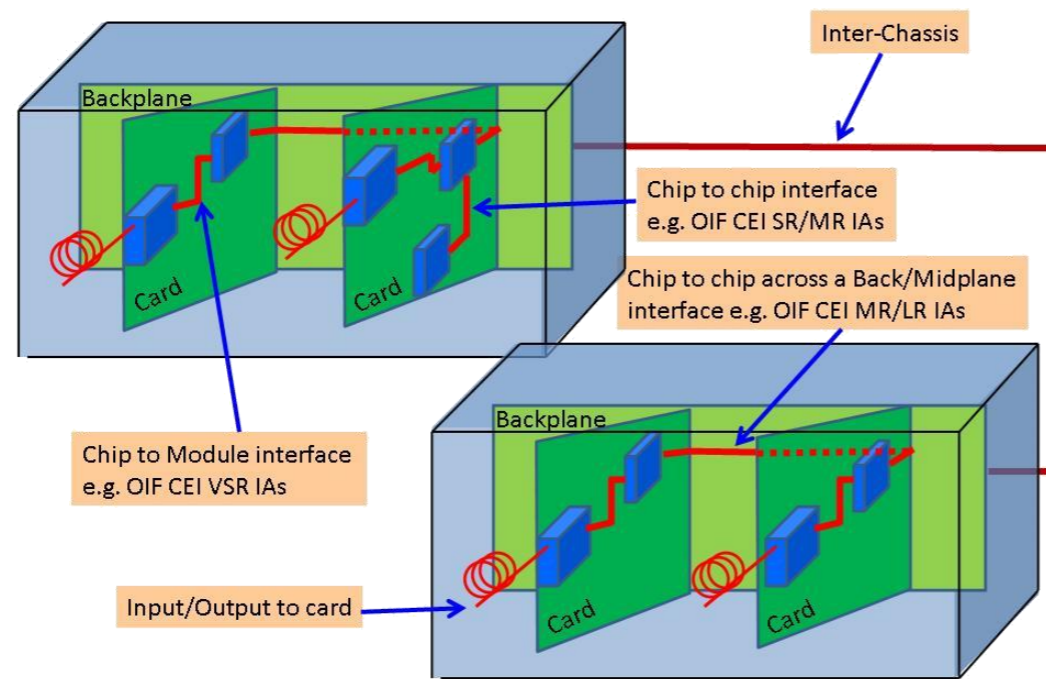
Kandou Bus SA

March 22, 2016



CEI Application Space is Evolving

- The “OIF Next Generation Interconnect Framework” white paper lays out a roadmap for CEI-56G serial links.
 - 2.5D and 3D applications are becoming increasingly relevant.
 - Mid-plane architectures are increasingly used to limit channel loss.
 - High function ASICs (such as switch chips) are driving requirements for higher I/O density and lower interface power.



OIF CEI-56G Projects

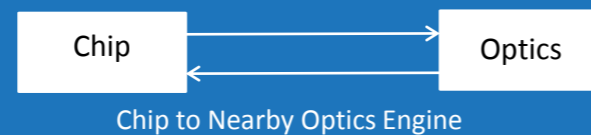
- CEI-56G Projects are underway for five link reach applications.
- Each reach optimizes the link budget with the goal of providing the lowest possible power dissipation for the application.

CEI-56G-USR



USR: 2.5D/3D die-to-die applications
• 1 cm, no connectors, no packages

CEI-56G-XSR



XSR: Chip to nearby optics engine or LR driver chip
• 5 cm, no connectors
• 5-10 dB loss at 28 GHz

CEI-56G-VSR



VSR: Chip-to-Module interfaces
• 10 cm, 1 connector
• 10-20 dB loss at 28 GHz

CEI-56G-MR



MR: Interface for chip-to-chip and midrange backplane
• 50 cm, 1 connector
• 15-25 dB loss at 14 GHz
• 20-50 dB loss at 28 GHz

CEI-56G-LR



LR: Interface for chip-to-chip over a backplane
• 100 cm, 2 connectors
• 35 dB loss at 14 GHz

Optimal Power for the Application

- Power has become the key cost driver in system design.
- Power requirements are driving standards to optimize link budgets for each application space.
 - Driver amplitude
 - Signal processing (FIR, DFE, FEC)
 - Clocking (CDR vs. Common or Forwarded Clock)
- Past practice of using one or two SerDes designs across a wide range of application spaces is no longer feasible.
 - Number of links on switch chips may preclude using LR Serdes.
 - Using USR/XSR interfaces to connect switch chips to off-board Optics Engines or LR Repeater Chips reduces power on the switch chip.

CEI-56G-USR	CEI-56G-XSR	CEI-56G-VSR	CEI-56G-MR	CEI-56G-LR
<< 1 pJ/bit	< 1.5 pJ/bit	< 2.5 pJ/bit	< 5 pJ/bit (incl. FEC)	< 7 pJ/bit (incl. FEC)

- Kandou has presented papers on very low power die-to-die interfaces using advanced modulation: “A Pin-Efficient 20.83Gb/s/wire 0.94 pJ/bit Forwarded Clock CNRZ-5-Coded SerDes up to 12mm for MCM Packages in 28nm CMOS”, Shokrollahi, et al., ISSCC 2016 Session 10.



HPC and Networking Applications Diverging

- CEI has been successful as the central specification for SerDes.
 - CEI-based SerDes are available in all major FPGA and ASIC flows.
 - Many public and proprietary CPU-CPU, CPU-I/O, and CPU-Memory interconnects are based on CEI SerDes.
- These interconnects typically use small SRAM or register-based transaction buffers.
 - Credit based flow control is used to avoid overflows.
 - CRC error detection and retry is used to handle errors.
- Credit based flow control is sensitive to latency.
 - Typical range of the bandwidth-delay product is 20-200 bytes.
 - Latency of Ethernet RS FECs exceed these limits and would force redesign to include larger buffers.
 - For some protocols buffers would need to be larger than the limits supported by the protocol.
- **Conclusion: HPC applications are creating a demand for alternative standards that are not dependent on FEC to achieve the link budget.**



CEI-56G Electrical Modulation Variants

- OIF is pursuing multiple modulation variants for several reach applications.
- Networking applications (802.3, T11.2) include FEC. Most PAM-4 variants assume FEC is implemented and optimize power/cost based on this assumption.
- Data center applications using token-based protocols cannot tolerate latency associated with FEC. NRZ variants support reasonable BER without utilizing FEC.
- ENRZ provides a “no FEC” option for higher loss applications where NRZ does not work.

Interface	Mod.	Max. Data Rate	IL @Nyquist	Clock Arch.	Elec. BER
CEI-56G-XSR-PAM4	PAM-4	58.0 Gb/s	4.25 dB	Fwd Clk	10 ⁻¹⁵
CEI-56G-VSR-PAM4	PAM-4	58.0 Gb/s	10 dB	CDR	10 ⁻⁶
CEI-56G-MR-PAM4	PAM-4	58.0 Gb/s	19.67 dB	CDR	10 ⁻⁶
CEI-56G-LR-PAM4	PAM-4	60.0 Gb/s	28.45 dB	CDR	3 x 10 ⁻⁴
PRELIMINARY – Subject to Change					

Interface	Mod.	Max. Data Rate	IL @Nyquist	Clock Arch.	Elec. BER
CEI-56G-USR-NRZ	NRZ	58.0 Gb/s	2 dB	Fwd Clk	10 ⁻¹⁵
CEI-56G-XSR-NRZ	NRZ	58.0 Gb/s	8 dB	Fwd Clk	10 ⁻¹⁵
CEI-56G-VSR-NRZ	NRZ	56.0 Gb/s	20 dB	CDR	10 ⁻¹⁵
CEI-56G-MR-NRZ	NRZ	56.0 Gb/s	30 dB	CDR	10 ⁻¹⁵
CEI-56G-LR-ENRZ	ENRZ	112.4 Gb/s (4 wires)	33.59 dB	CDR	10 ⁻¹⁵
PRELIMINARY – Subject to Change					



ENRZ Multiwire Code

ENRZ is a 3-bit over 4-wire Chord™ signaling code that fills the space between single-ended and differential signaling

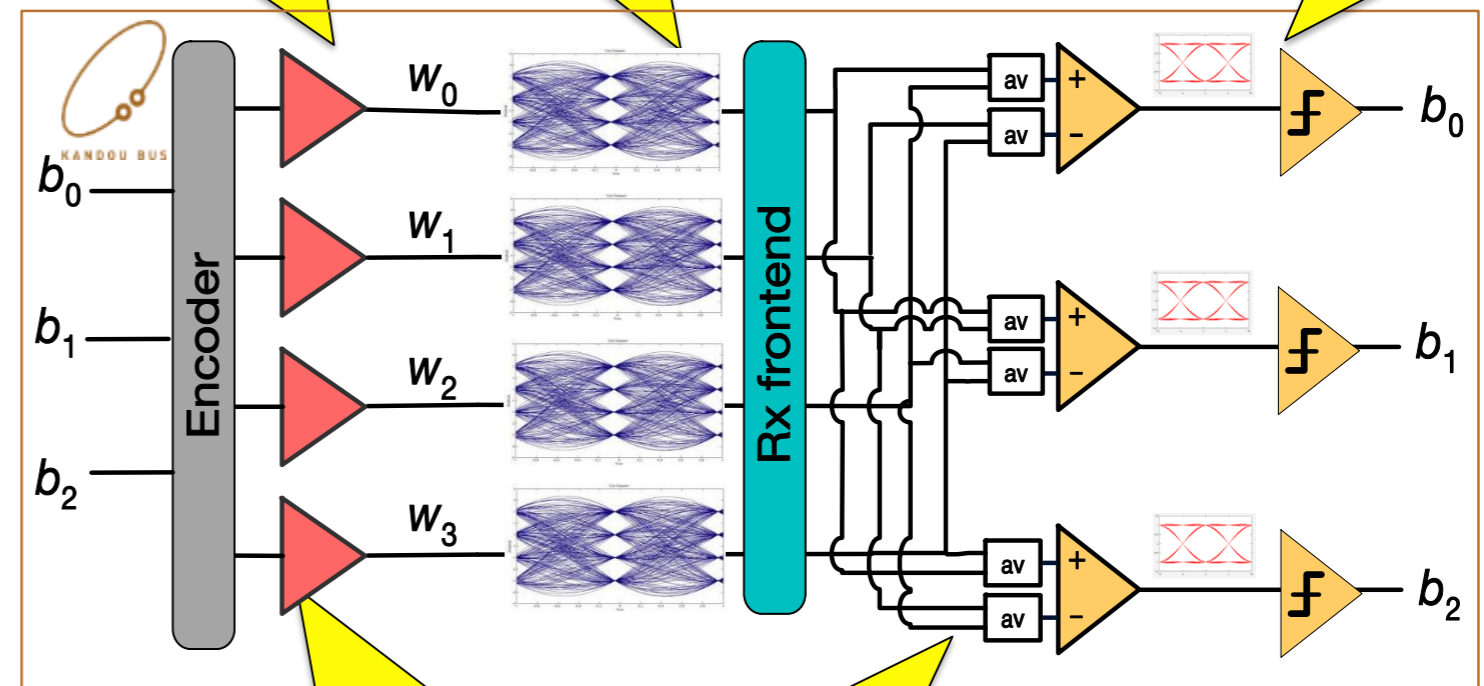
- Bandwidth per wire is higher than differential NRZ at similar baud rate.
- Inter-symbol interference is lower than PAM-4/8 interfaces
- Noise rejection characteristics are similar to differential signals

Because of signal integrity advantages, ENRZ does not require a FEC as is required for other LR variants.

Encoder Codes 3 bits as permutations of $\pm(+1, -1/3, -1/3, -1/3)$

Encoding results in Quaternary values on wires

Binary NRZ values at slicers do not have ISI issues inherent in PAM.

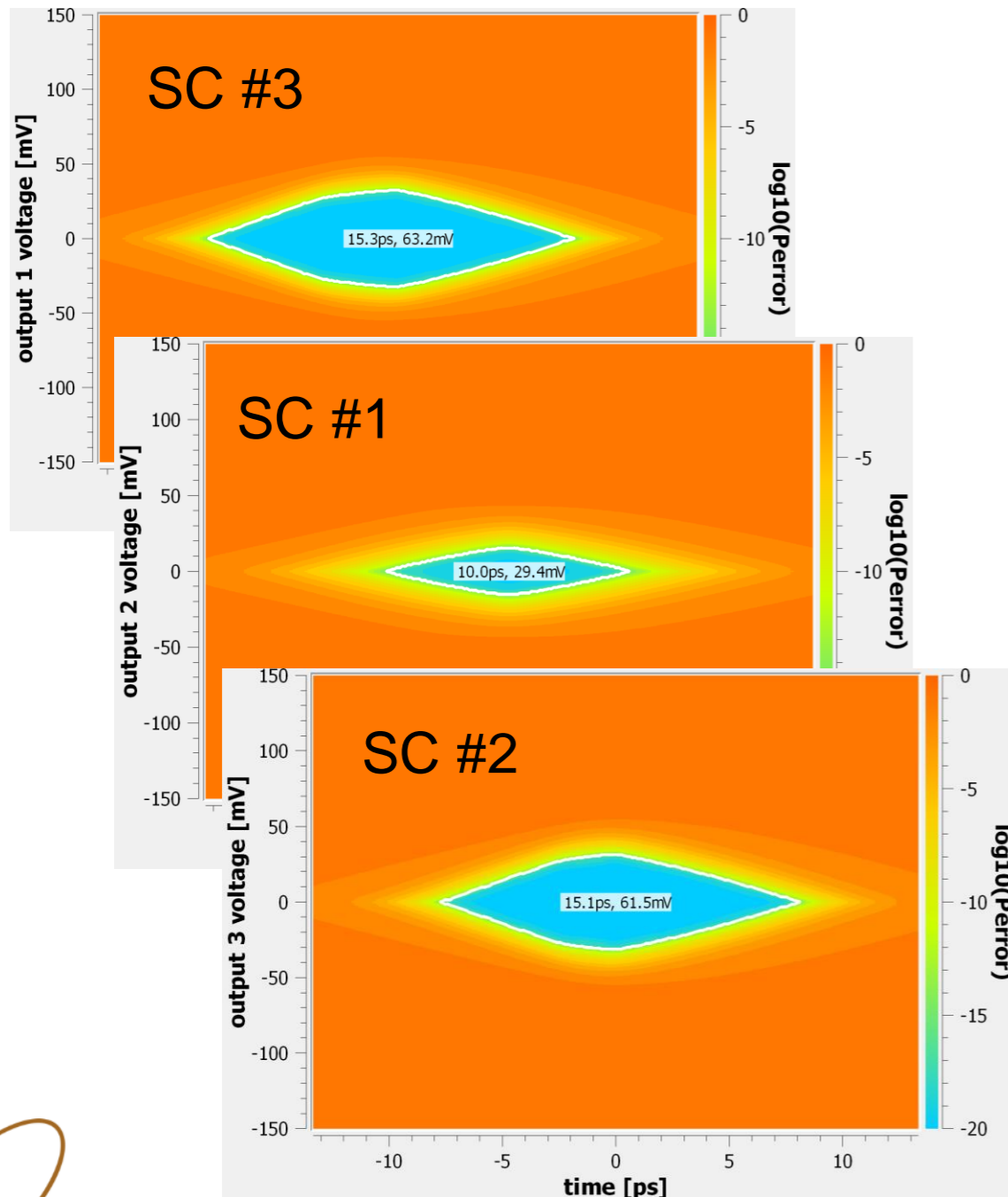


Balanced driver current reduces SSO and limits generated EMI

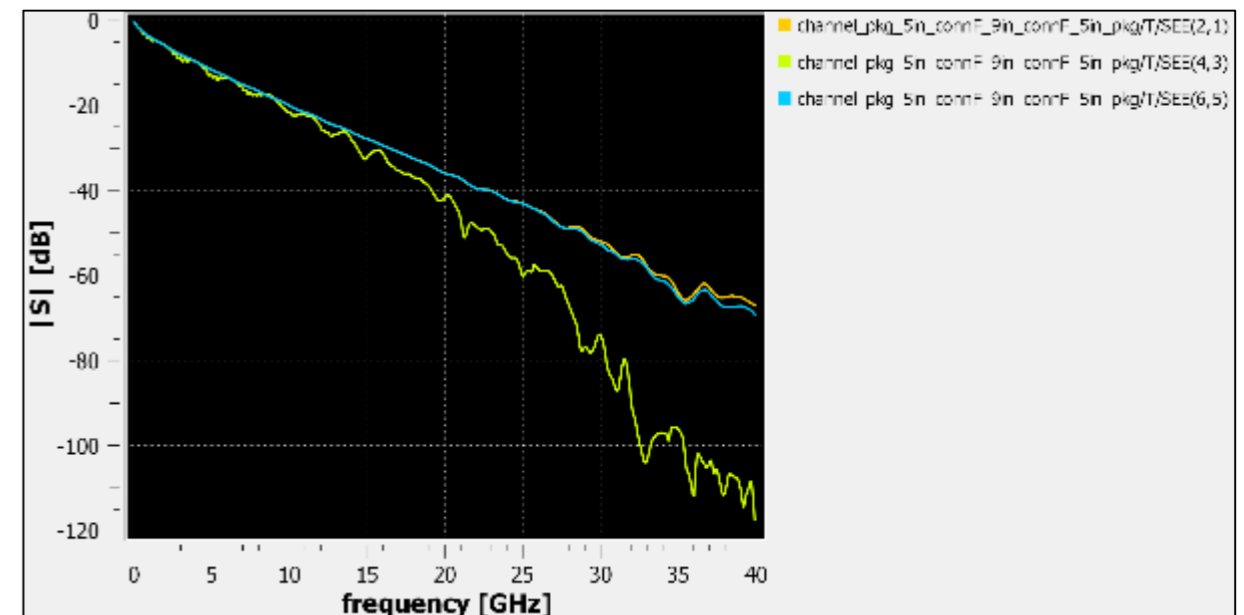
Linear combination stage averages signals prior to comparator and sampler.



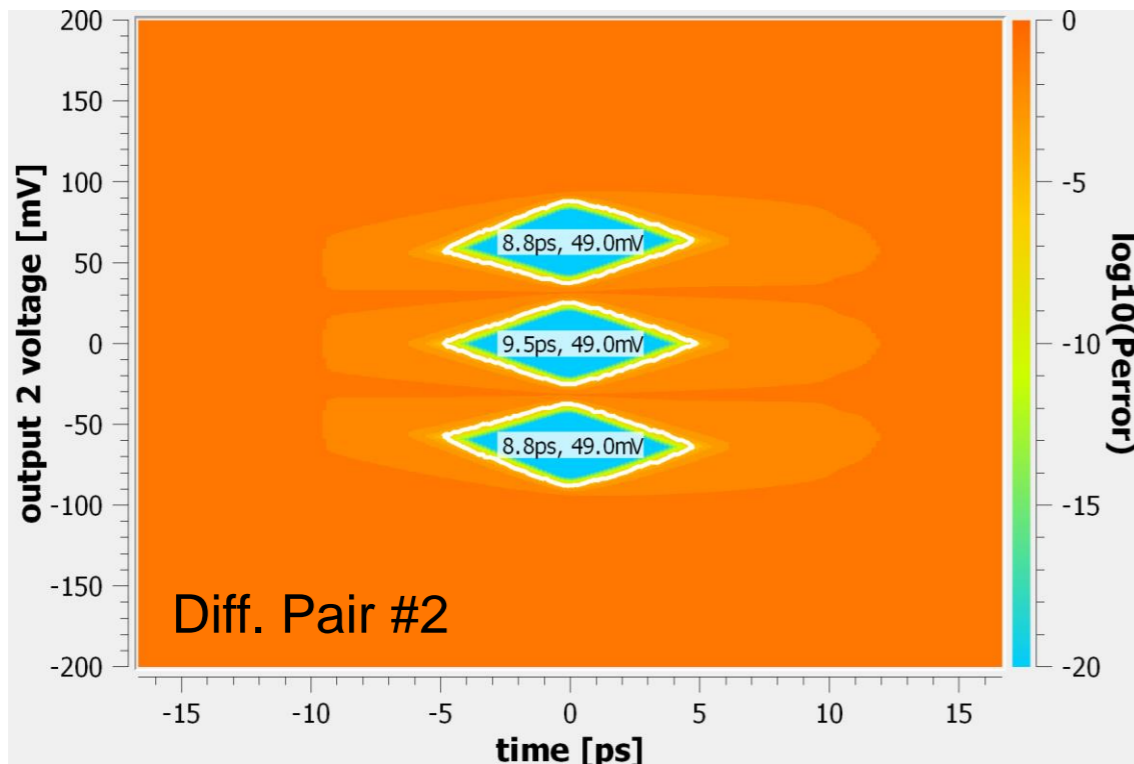
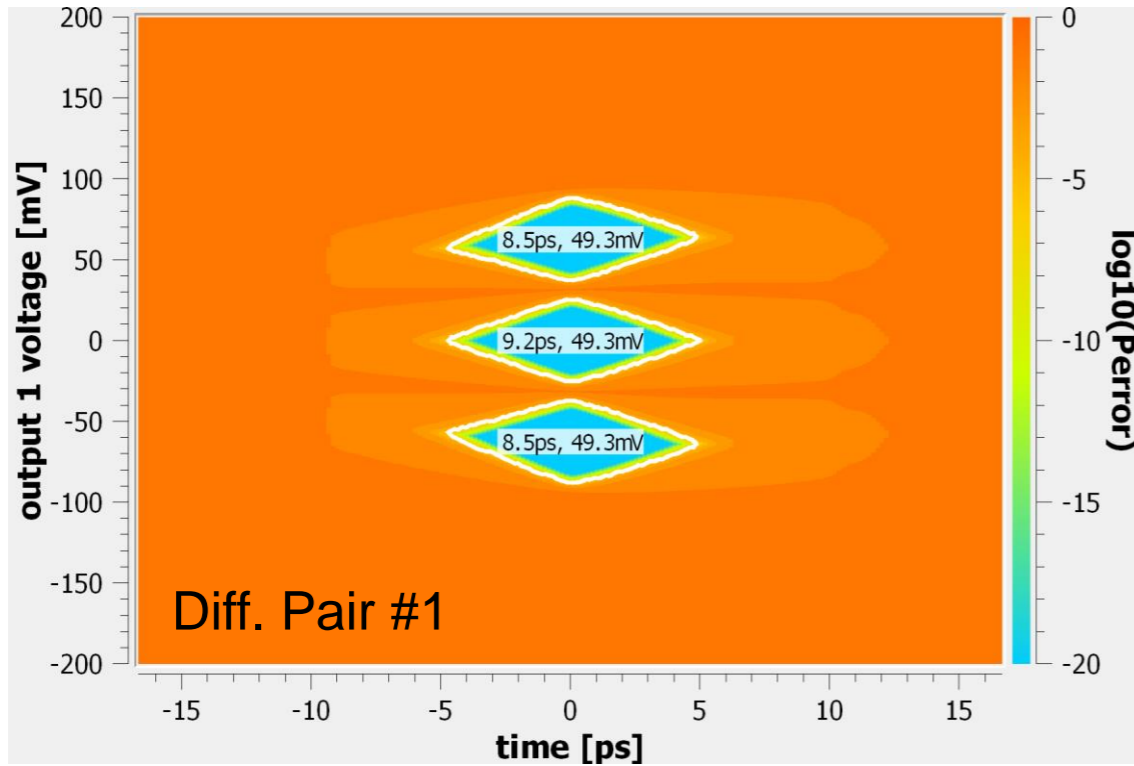
LR Channel Simulation Using ENRZ without FEC



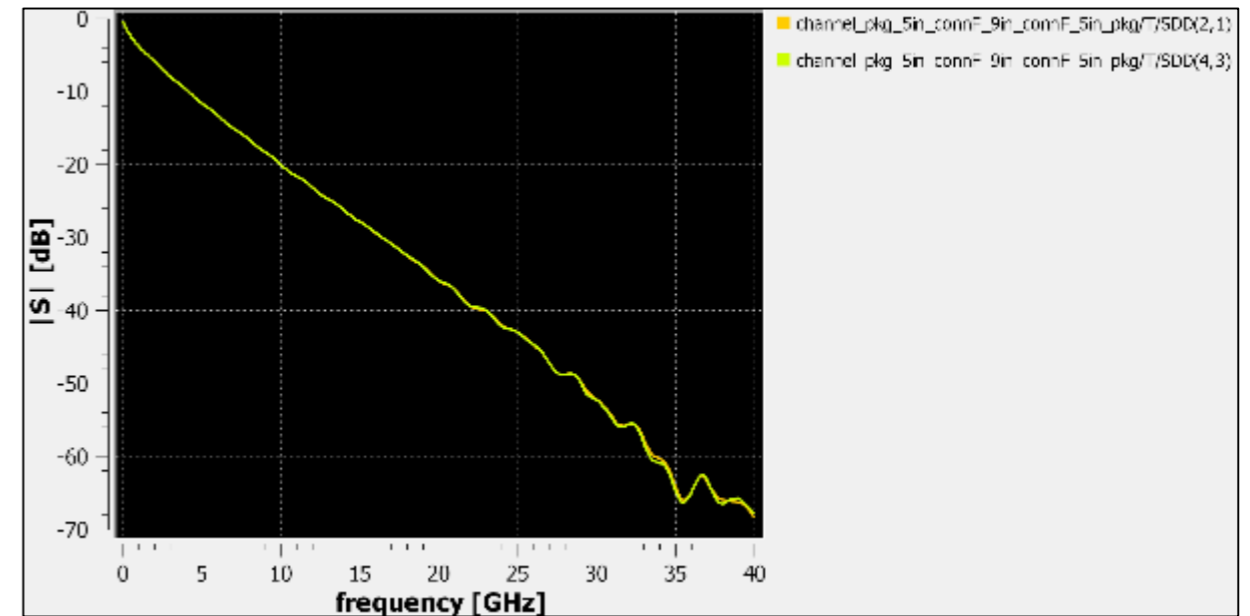
- Simulation conditions:
 - ENRZ @37.5 GBd
 - Tx Launch: 1000 mVppd
 - FFE (3-tap), VGA (10 dB), CTLE (4 dB), DFE (20-tap)
 - BER = 1E-15 (no FEC)
- Results:
 - EH: 29.5 mV (SC#2)
 - EW: 0.375 UI (SC#2)
- Conclusion:
 - SC#2 has sufficient eye opening.
 - No FEC is required.



LR Channel Simulation Using PAM4 with FEC



- Simulation conditions:
 - PAM-4 @30 GBd
 - Tx Launch: 1000 mVppd
 - FFE (3-tap), VGA (10 dB), CTLE (12 dB), DFE (20-tap)
 - BER = 1E-6 (assumes FEC)
- Results:
 - EH: 49.0 mV (pair #2)
 - EW: 0.255 UI (pair #1)
- Conclusion:
 - PAM-4 is a viable option, but requires FEC.



Summary and Conclusions

- Power requirements are driving standards to optimize link budgets for each application space.
- The selection of PAM-4 modulation (which is dependent on FEC) by networking applications has forced a divergence between interface standards for networking and HPC interface applications.
- NRZ modulation can handle interface reaches up to MR without requiring FEC.
- ENRZ provides a “No FEC” solution for LR interfaces.
- **OIF 100G Serial and Beyond Workshop on March 24th will explore next generation CEI-112G interfaces.**
 - **Kandou Bus will be presenting Chord™ signaling architectures for 112G and 224G in this workshop.**



KANDOU

reinventing the

BUS

